

L Number	Hits	Search Text	DB	Time stamp
1	1914	flexible near wiring near board	USPAT; EPO; JPO; DERWENT; USOCR	2004/01/10 16:30
2	663	electrolytic adj plating adj method	USPAT; EPO; JPO; DERWENT; USOCR	2004/01/10 16:33
3	0	(flexible near wiring near board) and (electrolytic adj plating adj method)	USPAT; EPO; JPO; DERWENT; USOCR	2004/01/10 16:31
4	5551	flexible near board	USPAT; EPO; JPO; DERWENT; USOCR	2004/01/10 16:31
5	2	(flexible near board) and (electrolytic adj plating adj method)	USPAT; EPO; JPO; DERWENT; USOCR	2004/01/10 16:32
6	14934	flexible near substrate	USPAT; EPO; JPO; DERWENT; USOCR	2004/01/10 16:33
7	14	(flexible near substrate) and (electrolytic adj plating adj method)	USPAT; EPO; JPO; DERWENT; USOCR	2004/01/10 16:33
8	7	(electrolytic adj plating adj method) near hole\$4	USPAT; EPO; JPO; DERWENT; USOCR	2004/01/10 16:38
9	0	(electrolytic adj plating adj method) near hole\$4 near (metal adj plug)	USPAT; EPO; JPO; DERWENT; USOCR	2004/01/10 16:39
10	96	(metal adj plug\$4) near hole\$4	USPAT; EPO; JPO; DERWENT; USOCR	2004/01/10 16:39
11	1	((metal adj plug\$4) near hole\$4) and (electrolytic adj plating adj method)	USPAT; EPO; JPO; DERWENT; USOCR	2004/01/10 16:40
13	26	174/\$.ccls. and (electrolytic adj plating adj method)	USPAT; EPO; JPO; DERWENT; USOCR	2004/01/10 16:40
12	26	361/\$.ccls. and (electrolytic adj plating adj method)	USPAT; EPO; JPO; DERWENT; USOCR	2004/01/10 16:40